| for p | s product specificatior | Pitch Double Row Breakaway Pin contains the test method, the general connector with 2007,2028,2037 series kaway socket. | performance and requirements | | |
|---|--|--|------------------------------|--|--|
| 1. | Construction and dimensions shall be in accordance with the referenced drawings. | | | | |
| | 产品结构和尺寸依据所涉及的产品图面. | | | | |
| 2. | | | | | |
| Current rating 额定电流: 2A DC Voltage rating 额定电压:250V AC | | | | | |
| | • • | a⊥ 2000 AC | | | |
| 3. | Electrical performance 电气特性: | | | | |
| ITEM | 」 DESCRIPTION 内容 | | REQUIREMENT 需求 | | |
| 3-1 | Contact Resistance | It should be tested in accordance with | 20 mΩ max. | | |
| | 接触阻抗 | method EIA-364-23. | | | |
| 3-2 | Insulation | It should be tested in accordance with | 1000 MΩ min. | | |
| | Resistance | method EIA-364-21. | | | |
| | 绝缘阻抗 | | | | |
| 3-3 | Dielectric | Unmated connectors shall be tested in | No evidence of breakdown | | |
| | withstanding | accordance with method EIA-364-20 | and flashover | | |
| | Voltage | when the AC 500 V rms for one minute | | | |
| | 耐电压 | applied between adjacent contacts. | | | |
| 4. | Mechanical Perform | ance 机械特性: | | | |
| ITEM | DESCRIPTION 内容 | TEST METHOD & CONDITION | REQUIREMENT 需求 | | |
| 4-1 | Post retention force | Push pin from insulator base at speed | 0.6kgf/pin. min | | |
| | 保持力 | 25mm/minute. | | | |
| 4-2 | Contact removal | Contact inserted in a housing shall be | 0.6kgf/pin. min | | |
| | force 接触拔出力 | pulled in an axis at a constant speed of 25 mm /minute. | | | |
| | 1女服1汉山刀 | | | | |
| 4-3 | Insertion | Housing with contact mating header at | 0.40kgf/pin. max | | |
| | Force | a constant speed of 25 mm / minute. | | | |
| | 插入力 | Use in 0.64mm(0.025")square pin. | | | |
| | | | | | |
| | | | | | |

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| Item 4-4 | Description 内容 Withdrawal Force 拨出力 | Test Method & Condition Housing with contact mating header, Pull out from header at speed 25mm / minute. Use in 0.64mm(.025")square pin. | Requirement 需求 0.02kgf/pin. min | | | |
|-----------------------------------|--|--|---|--|--|--|
| 4-5 | Durability 耐久性 | It should be tested in accordance with method EIA-364-09. Connector shall be subjected to 100 cycles of insertion and withdrawal | No defects. Contact resistance shall be 40 mΩ max. | | | |
| 4-6 | Vibration 振动 | The connector mated PCB shall be vibrated in accordance with method EIA-364-28 .There shall be no current discontinuity longer than 1 microsecond during the test . Frequency: 10-55-10 Hz / min. Amplitude: 1.52mm Period: 2 hours for each direction. | No evidence of loosening of parts or electric discontinuity. Contact resistance less than twice of initial. | | | |
| 5. Environmental Performance:环境特性 | | | | | | |
| 5-1 | Humidity 耐湿性 | The unmated connector shall be tested in accordance with method EIA-364-31. Temperature: 40±2 °C Humidity: 90 ~ 95 % (RH) Period: 96 hours. | No damage. Contact resistance: Less than twice of initial. Insulation resistance: paragraph 3-2. Dielectric withstanding voltage: to pass paragraph 3-3. | | | |

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| Item | Description 内容 | Test Method & Condition | Requirement 需求 |
|------|--|---|--|
| 5-2 | Thermal shock 冲击 | Connector shall be subjected to thermal shock cycling in accordance with method EIA-364-27. one cycle consists of:-25 $^{\circ}$ C for 30 minutes. +105 $^{\circ}$ C for 30 minutes. Times of cycle:25 cycles. | No damage. Contact resistance: Less than twice of Initial. Insulation resistance: paragraph 3-2. Dielectric withstanding voltage: to pass paragraph 3-3. |
| 5-3 | Salt Spray 盐雾试验 | Connector shall be tested in accordance with method EIA-364-26. Temperature: 35±2 °C Density: 5 % in weight. Period: 24 hours. | No damage Contact resistance: Less than twice of initial. |
| 5-4 | Solder ability 着锡性 | Connector termination ends shall be checked for solderadility in accordance with method EIA-364-52. Solder temperature: 245±5 °C Immersion period: 5±0.5 sec. | No damage. Minimum: 95% of immersed area. |
| 5-5 | Resistance to soldering heat 耐高温焊接 | Specimen shall be mounted on PCB Solder temperature : 260±5°C Immersion period : 5±0.5sec. | No damage and deformation. |
| | | | |
| APPR | BY:Chard 2018.11.1 | 5 CHKD BY:Shirley 2018.11.15 | SPEC BY: Spring 2018.11.15 |